

IN THE CLAIMS:

Claims 1, 4, 7, 10, 13, 16, and 19 have been amended herein. All of the pending claims 1 through 21 are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

Listing of Claims:

1. (Currently Amended) An automolding system comprising:
providing a substrate having a surface having a layer of resist on a portion thereof in the automolding system; ~~and~~
removing at least a portion of the layer of resist and at least a portion of the contaminants from the substrate using a laser in the automolding system; and
scanning the substrate using a laser in the automolding system for irregularities from removing the layer of resist.
2. (Previously Presented) The automolding system of claim 1, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.
3. (Previously Presented) The automolding system of claim 1, further comprising:
a mold; and
encapsulating the substrate in the mold in the automolding system.
4. (Currently Amended) A molding system comprising:
providing a substrate having a surface having a layer of resist on a portion thereof in the molding system;
removing at least a portion of the layer of resist and contaminants from the substrate using a laser in the the molding system; and
scanning the substrate using a laser in the automolding system for irregularities from removing the layer of resist.

5. (Previously Presented) The molding system of claim 4, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.
6. (Previously Presented) The molding system of claim 4, further comprising:
a mold in the molding system for encapsulating the substrate.
7. (Currently Amended) A system for molding comprising:
providing a substrate having a surface having a layer of resist on a portion thereof for molding in the system;
cutting a portion of the layer of resist using a laser in the molding system; and
removing at least a portion of the layer of resist and some contaminants from the substrate using a laser in molding system.
8. (Previously Presented) The system of claim 7, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.
9. (Previously Presented) The system of claim 7, further comprising:
a mold in the system for encapsulating the substrate.
10. (Currently Amended) An automolding system comprising:
placing a substrate having a surface having a layer of resist on a portion thereof in the automolding system;
cutting a portion of the layer of resist using a laser in the molding system; and
removing at least a portion of the layer of resist and at least some of the contaminants from the substrate using a laser in the automolding system.
11. (Previously Presented) The automolding system of claim 10, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

12. (Previously Presented) The automolding system of claim 10, further comprising:
a mold for encapsulating the substrate in the automolding system.

13. (Currently Amended) In a molding system comprising:
placing a substrate having a semiconductor device thereon, the substrate having a surface having
a layer of resist on at least a portion thereof in the molding system; ~~and~~
removing at least a portion of the layer of resist and at least some of the contaminants from the
substrate using a laser in the molding system; and
marking a surface of the semiconductor die using the laser in the molding system .

14. (Previously Presented) In the molding system of claim 13, wherein the laser
comprises one of an Nd:YAG laser and an excimer laser.

15. (Previously Presented) In the molding system of claim 13, further comprising:
a mold in the molding system for encapsulating the substrate.

16. (Currently Amended) A system for molding comprising:
placing a substrate having a semiconductor device thereon, the substrate having a surface having
a layer of resist on at least a portion thereof for molding in the system; ~~and~~
removing at least a portion of the layer of resist and at least some of the contaminants from the
substrate using a laser in the automolding system; and
marking a surface of the semiconductor device using the laser in the automolding system.

17. (Previously Presented) The system of claim 16, wherein the laser comprises one
of an Nd:YAG laser and an excimer laser.

18. (Previously Presented) The system of claim 16, further comprising:
a mold in the system for encapsulating the substrate.

19. (Currently Amended) An automolding system having a cleaning apparatus comprising:
introducing a substrate having a semiconductor device thereon, the substrate having a surface having a portion thereof covered with a layer of resist in the automolding system;
cutting a portion of the layer of resist; and
removing at least a portion of the layer of resist and at least some of the contaminants from the substrate using a laser in the automolding system; and
marking a surface of the semiconductor device using the laser in the automolding system.

20. (Previously Presented) The automolding system of claim 19, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

21. (Previously Presented) The automolding system of claim 19, further comprising:
a mold for encapsulating the substrate in the automolding system.

22. through 40. (Canceled)